

Micro G Switch **Bottom Contact** Model AT-27-B

FEATURES:

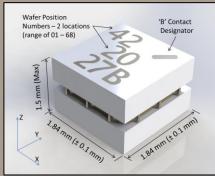
- Small and Lightweight 3.4 mm²

- Surface Mount Au over Ni Pads
- Tape and Reel Packaging
- Environmental Seal

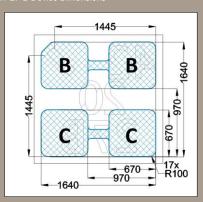
APPLICATIONS:

- Arming / Fuzing
- More





AT-27-B Device Dimensions



AT-27-B Pad Dimensions (micrometers) as viewed from **PAD** side of device

Specifications

OPERATING CHARACTERISTICS:

Sensitivity	+Z (normal to PCB)	
Contact Acceleration Threshold	, ,	
No Go	18	g
All Go	27	g
Contact Type (3)	Normally Open, Non-Latching	Ü
Response Time (2)	< 400	μS
Reset		•
ELECTRICAL CHARACTERISTICS		
Contact Resistance (1)	< 10	ohms
Insulation Resistance		Mohr

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Contact Resistance (1) < 10	ohms
Insulation Resistance>1000	Mohm
Breakdown Voltage>200	VDC

ENVIRONMENTAL RATINGS:

Operate Temperature Range55 to +125	°C
Storage Temperature Range55 to +125	°C
PCB/Pad Shear Force>20	N
Shock Survival (4)	g

PHYSICAL CHARACTERISTICS:

Nominal Dimensions (LxWxH)	. 1.84 x 1.84 x 1.3	mm
Volume	3.7	mm^3
Mass	20	milligrams
ROHS Compliant ?	Yes	Ü

- (1) Contact resistance is dependent on input pulse acceleration level.
- Response time depends upon input pulse profile and magnitude. Response time shown is for acceleration step of 100g.
- Electrical connection between pads B (bottom) and C (common) is normally open and is closed while acceleration is greater than the contact acceleration threshold.
- The Micro G Switch devices are designed to survive the extreme high shock environments associated with artillery launch events.

Note that the information on this data sheet is for reference only.

As each application may have unique requirements, please verify the specifications as well as suitability of using our products in your applications by consulting our engineering department.

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